

**IN THE CLAIMS**

Please amend the claims as follows:

1-10. (Canceled)

11. (Previously presented) An epitaxial growth method comprising:

growing an epitaxial layer on a layered substrate,

wherein the layered substrate comprises sapphire on silicon and the epitaxial layer comprises group III nitrides.

12-23. (Canceled)

24. (Previously presented) The epitaxial growth method of claim 11 further comprising the step of removing the layered substrate after growing the epitaxial layer.

25. (Previously presented) The epitaxial growth method of claim 24 wherein the step of removing comprises mechanical polishing.

26. (Previously presented) The epitaxial growth method of claim 11 wherein a process of forming said layered substrate includes a heating step, wherein said layered substrate exhibits the bowing after being cooled down from said heating step.

27. (Canceled)

28. (Previously presented) The epitaxial growth method of claim 11, wherein the thickness of the silicon is less than 6 microns, the thickness of the epitaxial layer is less than 3 microns and the wafer bowing is less than  $0.5 \text{ m}^{-1}$ .

29. (Previously presented) The epitaxial growth method of claim 11, wherein the thickness of the silicon is from 2 to 10 microns, the thickness of the epitaxial layer is from 3 to 10 microns and the wafer bowing is less than  $0.5 \text{ m}^{-1}$ .

30. (Previously presented) The epitaxial growth method of claim 11, wherein the thickness of the silicon is from 20 to 30 microns, the thickness of the epitaxial layer is from 40 to 60 microns and the wafer bowing is less than  $0.5 \text{ m}^{-1}$ .

31. (New) An epitaxial growth method comprising the step of:  
growing an epitaxial layer on a layered substrate, wherein the layered substrate comprising sapphire on silicon exhibits bowing in a convex manner, and  
flattening the epitaxial layer having a III-V nitrides alloy and the layered substrate after the epitaxial layer is grown on the layered substrate.

32. (New) The epitaxial growth method of claim 31, wherein  
an AlN buffer layer is grown on the layered substrate prior to growing the epitaxial layer  
thereon, and  
the AlN buffer layer is grown at a temperature lower than that of the epitaxial layer.